

WHAT IS CLAIMED IS:

1. A thermal conductive material comprising an organic material and a filler having higher thermal conductivity than the organic material, wherein said thermal conductive material is plasticized at least at the generally-used temperature in the range of 30-65°C and changes its form flexibly corresponding to the surface form of a member with which it comes in contact.
2. A thermal conductive material set forth in claim 1, wherein said thermal conductive material is plasticized at 60°C under pressure equal to or above 6.0g/cm<sup>2</sup> and changes its form flexibly corresponding to the surface form of a member with which it comes in contact.
3. A thermal conductive material set forth in claim 1, wherein said thermal conductive material satisfies the following conditions (a-c):
- a. the melting point of said organic material is in the range of 30-70°C;
  - b. the viscosity of said organic material at 100°C is equal to or above 70,000cP; and
  - c. the ratio of said filler to the whole thermal conductive material is in the range of 30-90 weight %.

4. A thermal conductive material set forth in claim 1, wherein said thermal conductive material is in a rubber-like state at room temperature.

5 5. A thermal conductive material set forth in claim 1, wherein said organic material is olefin resin.

6. A thermal conductive material set forth in claim 2, wherein said organic material is unvulcanized EPDM having  
10 7,000-50,000 molecular weight.

7. A thermal conductive material set forth in claim 1, wherein said filler is of at least one of ceramics, metallic powder, metallic magnetic body and carbon fiber.

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*PNRM.*

8. A thermal conductive material set forth in claim 1, wherein a material serving as an electromagnetic shield is used as said filler.

20 9. A method for producing a thermal conductive material comprising an organic material and a filler having higher thermal conductivity than the organic material, wherein said thermal conductive material is plasticized at least at the generally-used temperature in the range of 30-65°C and changes  
25 its form flexibly corresponding to the surface form of a member

with which it comes in contact, the method comprising the steps of:

kneading a filler and an organic material; and  
molding said kneaded material.

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